PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Scott Jay Crane	10/03/2008
Simon J.S. McElrea	09/22/2008
Scott McGrath	09/22/2008
Weiping Pan	09/22/2008
De An Eileen Melcher	09/30/2008
Marc E. Robinson	09/22/2008

RECEIVING PARTY DATA

Name:	Vertical Circuits, Inc.
Street Address:	10 Victor Square
City:	Scotts Valley
State/Country:	CALIFORNIA
Postal Code:	95066

PROPERTY NUMBERS Total: 2

Property Type	Number
Application Number:	12199080
Application Number:	60971203

CORRESPONDENCE DATA

500671355

Fax Number: (650)712-0263

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 6507120340

Email: npannoni@hmbay.com

Correspondent Name: Bill Kennedy
Address Line 1: 637 Main Street

Address Line 4: Half Moon Bay, CALIFORNIA 94019

ATTORNEY DOCKET NUMBER: VCIX 1040-2

PATENT

REEL: 021659 FRAME: 0576

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NAME OF SUBMITTER:	Bill Kennedy
Total Attachments: 3	
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PATENT REEL: 021659 FRAME: 0577

JOINT TO CORPORATE ASSIGNMENT

WHEREAS, the undersigned,

- (1) Scott Jay Crane (2) Simon J.S. McElrea 19388 Oak Ridge Drive 621 Acorn Court Aromas, CA 95004 Scotts Valley, CA 95066
- (3) Scott McGrath (4) Weiping Pan 13 Terrace View Court 1116 Johnson Avenue Scotts Valley, CA 95066 San Jose, CA 95129
- (5) De An Eileen Melcher (6) Marc E. Robinson 6006 Guadalupe Mines Road 1235 Valley Quail Circle San Jose, CA 95120 San Jose, CA 95120

hereinafter termed "Inventors", have invented certain new and useful improvements in

SEMICONDUCTOR DIE MOUNT BY CONFORMAL DIE COATING

and have filed a provisional application for a United States patent disclosing and identifying the above invention on 10 September 2007 as Application No. 60/971,203, and have filed a non-provisional application for a United States patent disclosing and identifying the above invention on 27 August 2008 as Application No. 12/199,080, OR are filing such an application herewith, and have executed an oath or declaration of inventorship for such non-provisional application on:

(1) the 3rd day of October	, 2008;
(2) the	, 2008;
(3) the 22 day of SEP TEMBER	
(4) the 22 day of September	, 2008;
(5) the 30 day of September	, 2008;
(6) the 22 day of Septenber	

(hereinafter termed "applications"); and

WHEREAS, <u>Vertical Circuits</u>, <u>Inc.</u>, a corporation of <u>Delaware</u>, having a place of business at <u>10 Victor Square</u>, <u>Scotts Valley</u>, <u>CA 95066</u> (hereinafter termed "Assignee"), is desirous of acquiring the entire right, title and interest in and to said applications and the invention disclosed therein, and in and to all embodiments of the invention, heretofore

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conceived, made or discovered by said Inventor (all collectively hereinafter termed "said invention"), and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter termed "patents") thereon granted in the United States and foreign countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Inventors to have been received in full from said Assignee:

- 1. Said Inventors do hereby sell, assign, transfer and convey unto said Assignee the entire right, title and interest (a) in and to said applications and said invention; (b) in and to all rights to apply for foreign patents on said invention pursuant to the International Convention for the Protection of Industrial Property or otherwise, including the right to claim priority from the applications; (c) in and to any and all applications filed and any and all patents granted on said invention in the United States or any foreign country, including each and every application filed and each and every patent granted on any application which is a divisional, substitution, continuation, or continuation-in-part of any of said applications; and (d) in and to each and every reissue or extensions of any of said patents.
- 2. Said Inventors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest herein conveyed in the United States and foreign countries. Such cooperation by said Inventors shall include prompt production of pertinent facts and documents, giving of testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said invention; (d) for filing and prosecuting applications for reissuance of any said patents; (e) for interference or other priority proceedings involving said invention; and (f) for legal proceedings involving said invention and any applications therefor and any patents granted thereon, including without limitation reissues and reexaminations, opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Inventor in providing such cooperation shall be paid for by said Assignee.
- 3. The terms and covenants of this assignment shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Inventors, the inventors' respective heirs, legal representatives and assigns.
- 4. Said Inventors hereby warrant and represent that said inventors have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

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IN WITNESS WHEREOF, said Inventors have executed and delivered this instrument to said Assignee as of the date written below.

Weiping Pan

Marc E. Robinson

Date: _

Date:

9-22-2008

Date: 9-30-3008Date: 9/22/08